



Patent
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s) : Edward G. Combs *et al.*
Serial No. : 09/902,878 **Group Art Unit** : 2827
Filed : July 11, 2001 **Examiner** : A. Chambliss
For : *Enhanced Thermal Dissipation Integrated Circuit Package (As Amended)*

**AMENDMENT AND REQUEST FOR
RECONSIDERATION UNDER 37 C.F.R. § 1.111**

COMMISSIONER FOR PATENTS
Washington, D.C. 20231

Sir:

This Amendment and Request for Reconsideration is submitted in response to the Office Action mailed November 6, 2002. Please amend the above-referenced application as follows.

IN THE TITLE

Please replace the title with the following:

Enhanced Thermal Dissipation Integrated Circuit Package

IN THE SPECIFICATION AT PAGE 8, LINES 18-23

Please replace the paragraph at page 8, lines 18-23 with the following:

Further details of the heat sink 110 of a subassembly shown in FIG. 4B include extending fingers 116-1, 116-2, 116-3 and 116-4 of the support structure 114. As shown in plan view by FIG. 4B, the fingers 116-1, 116-2, 116-3 and 116-4 may be sized and shaped to engage matching wells or recesses 202-1, 202-2, 202-3 and 202-4 in the supporting walls of the carrier 200 (step 1125). Such fingers 116-1, 116-2, 116-3 and 116-4 in whole or in part support the heat